ASSIG



HEET

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document or copy thereof.

- 1. Names of conveying parties:
 - Yu-yen Mo a)
 - Manoj Gopalan b)
 - Venkat R. Podduturi c)
- 2. Name and address of receiving party:
 - Name:

Sun Microsystems, Inc.

b) Address: 4150 Network Circle Santa Clara, CA 95054

3.	Nature of conveyance				
	Assignment Security Agreement Other	☐ Merger ☐ Change of Name License Agreement			

Execution Dates: a) August 22, 2005; b) August 23, 2005; c) August 22, 2005.

4. Application Number: Not yet assigned

> The title of the new application is: FLIP-FLOP INSERTION METHOD FOR GLOBAL INTERCONNECT PIPELINING

5. Please send all correspondence concerning this document to:

> Albert S. Penilla, Esq. MARTINE PENILLA & GENCARELLA, LLP 710 Lakeway Drive, Suite 200 Sunnyvale, CA 94085 Customer No. 32291 Tel. No. (408) 774-6903 Fax No.: (408) 749-6901

- 6. Total number of applications and patents involved: 1
- 7. Total fee (37 CFR 3.41): \$40.00

Any deficiency is authorized to be charged to Deposit Account No. 50-0805

(Order No. SUNMP660)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: August 23, 2005

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Albert S. Penilla, Esq. Registration No. 39,487

Attorney Docket No. SUNMP660 / SUN050529

Revised 01/96)

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

FLIP-FLOP INSERTION METHOD FOR GLOBAL INTERCONNECT PIP ELINING

(Atty. Docket No. SUNMP660 / SUN050529) for which we have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventors hereby:

- 1) Sell, assign and transfer to <u>Sun Microsystems</u>, <u>Inc.</u>, a <u>Delaware</u> corporation having a place of business at <u>4150 Network Circle</u>, <u>Santa Clara</u>, <u>CA 95054 U.S</u>, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment,

Signed on the dates indicated beside our signatures.

1)	Signature: Typed Name:	Yu-yen Mo	Date:	222-05
2)	Signature: Typed Name:	Manoj Gopalan	Date:	
3)	Signature: Typed Name:	Venker R. Podduturi	Date:	8-22-5

Attorney Docket No. SUNMP660 / SUN050529

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Signed on the dates indicated beside our signatures.

1) Signature:
Typed Name: Yu-yen Mo

2) Signature:
Typed Name: Manoj Gopalan

3) Signature:
Typed Name: Venkat R. Poddunai

Attorney Docket No. SUNMP660 / SUN050529

RECORDED: 08/23/2005

PATENT REEL: 016922 FRAME: 0266